

singularly and independent from one another. These elements are to be viewed, therefore, as independent features.

Patent Claims

1. Device (1; 100) for processing substrates (2), in particular semi-conductor wafers, with at least one first nozzle (38; 152) essentially concentrically arranged relative to the substrate (2) and a plurality of second nozzles (18; 142) separately controllable relative to the first nozzle, characterized in that the first nozzle (38; 152) is directed perpendicularly onto the substrate (2), so that a fluid emerging from the first nozzle strikes the substrate and projects a radial flow onto the substrate, and in that the second nozzles are directed transverse to the radial flow.
2. Device (1; 100) according to claim 1 or 2, characterized in that the first nozzle (18; 152) is a single point nozzle.
3. Device (1; 100) according to any one of the preceding claims, characterized in that the second nozzles (18; 142; 144) form at least one nozzle group, which runs along a prescribed contour, especially a straight line.
4. Device (1; 100) according to claim 3, characterized in that the straight line extends tangential to the first nozzle (38; 152).
5. Device (1; 100) according to any one of the preceding claims, characterized in that at least one additional nozzle (156) is directed back at the first nozzle (152).

6. Device (1; 100) according to any one of the preceding claims, characterized in that the second nozzles (18; 142; 144) are directed onto the substrate at an angle of 45°.
7. Device (1; 100) according to any one of the preceding claims, characterized in that the second nozzles (18; 142, 144) are point nozzles.
8. Device (1; 100) according to any one of the preceding claims, characterized in that the first nozzle (18; 152) and the second nozzles (18; 142, 144) can have different pressures.
9. Device (1; 100) according to any one of the preceding claims, characterized in that the first nozzle (18; 152) and the second nozzles (18; 142; 144) can contain different fluids.
10. Device (1; 100) according to any of the preceding claims, characterized in that rinsing fluid can be conducted through the first nozzle (18; 152).
11. Device (1; 100) according to any one of the preceding claims, characterized in that a vacuum can be applied to the first nozzle (18; 152).
12. Device (1; 100) according to any one of the preceding claims, characterized in that a gas can be conducted through the second nozzles (18; 142; 144).